

A B S T R A C T

~~ELECTRONIC SUBSTRATE FOR A THREE-DIMENSIONAL ELECTRONIC MODULE~~

The invention relates to an electronic substrate [(5)] suitable for being included in a stack containing said electronic substrate and at least one other electronic substrate and suitable for being connected to the other electronic substrate[(s)] and optionally to an input-output interface [(31)], ~~characterized in that~~ wherein it comprises a frame [(10)] consisting of a material with a high thermal conductivity comprising a plurality of sides, ~~at least one~~ a first side [(11)] of which is intended to be in contact with the corresponding side of the frame of another ~~(or the other)~~ neighboring substrate[(s)] so as to provide thermal dissipation of the electronic substrates and ~~at least one~~ a second side [(12)] of which comprises an interconnection element [(120)] intended to provide electrical interconnection between said electronic substrate [(5)] and the other electronic substrate(s) by means of a routing circuit [(121)] ~~and/or~~ between said electronic substrate [(5)] and the input-output interface [(31)].

Fig 1a